

Count	RefDes	Value	Description	Size	PartNumber	Mfr
0	C10	open	Capacitor, Ceramic Chip, 50V, +/-0.25pF, 1.8pF		402 GRM1555C1H1R8BA01D	muRata
1	C11	0.3pF	Capacitor, Ceramic Chip, 50V, +/-0.05pF, 0.3pF		402 GRM1555C1HR30WA01#	muRata
2	C13 C16	2pF	Capacitor, Ceramic Chip, 25V, +/-0.25pF		402 GRM1555C1H2R0BZ01	muRata
12	C1-4 C12 C14-15 C17-18 C21-22 C29	0.1uF	Capacitor, Ceramic Chip, 6.3V, +/-10%		402 GRM152B30J104KE19	muRata
2	C19-20	27pF	Capacitor, Ceramic Chip, 50V, +/-5%		402 GRM1532C1H270JDD5	muRata
0	C23	open	Tantalum Solid Capacitors with Conductive Polymer (POSCAP), 330uF	6032 (C) STD		Sanyo
1	C24	330uF	Tantalum Solid Capacitors with Conductive Polymer (POSCAP), 330uF	6032 (C) STD		Sanyo
1	C25	4.7uF	Capacitor, Ceramic Chip, 6.3V, +/-10%		402 GRM155R60J475ME47	muRata
1	C26	10uF	Capacitor, Ceramic Chip, 6.3V, +/-20%		603 GRM188B30J106ME47	muRata
0	C27-28	open	Capacitor, Disc, 6.3V, Temp 15%, +/-20%	3528(B) STD		Sanyo
0	C5	open	Capacitor, Ceramic Chip, 6.3V, +/-10%		402 GRM152B30J104KE19	muRata
3	C7 C6 C8	2pF	Capacitor, Ceramic Chip, 50V, +/-0.25pF		402 GRM1555C1H2R0BZ01	muRata
1	C9	0.47uF	Capacitor, Ceramic Chip, 16V, +/-2%		402 GRM0222C1C150GD05	muRata
1	D1	BAT54LP	Diode, Schottky, 200-mA, 30-V	DFN-1006-2	BAT54LP	Diodes
1	D2	LTST-C190CKT	Diode, LED, Red, 2.1-V, 20-mA, 6-mcd	603	LTST-C190CKT	Lite On
3	D3-5	BAT54C	Diode, Dual Schottky, 200-mA, 30-V	SOT23	BAT54C	Vishay-Liteon
1	J1	TMS-106-XX-X-S-RA	Connector, 6pin	0.300x0.310	TMS-106-XX-X-S-RA	Samtec
1	L1	12nH	CER INDUCTOR 12NH 0402		402 L-07C12NJV4	Johanson Technology Inc
1	L2	22nH	CER INDUCTOR 22NH 0402		402 L-07C22NJV4T	Johanson Technology Inc
1	L3	2.2 uH	Inductor, SMT, xx mA, +/-20%		805 LQM21PN2R2N	muRata
1	Q1	Si1539CDL	MOSFET, N-Pch, 30V, 0.7A, 525 mOhms, 890 mOhms	SC-70	Si1539CDL	Vishay
1	R1	620k	Resistor, Chip, 1/16W, 1%		402 Std	Std
1	R2	1k	Resistor, Chip, 1/16W, 1%		402 Std	Std
1	R3	0R	Resistor, Chip, 1/16W, x%		201 Std	Std
1	R4	56k	Resistor, Chip, 1/16W, 1%		402 Std	Std
1	R5	1M	Resistor, Chip, 1/16W, 1%		402 Std	Std
0	R6	open	Resistor, Chip, 1/16W, 1%		402 Std	Std
1	R7	1M6	Resistor, Chip, 1/16W, 1%		402 Std	Std
1	R8	1M2	Resistor, Chip, 1/16W, 1%		402 Std	Std
1	S1	TS-A85-1	Switch, 1P1T, PB Momentary, 50-mA	0.114 x 0.212 inch	TS-A85-1	Contact Tech.
6	SOLAR CELL AM 25MM X 20MM	AM-5610CAR	SOLARCELL 5.1V 24mA		Sanyo AM5610CAR	Sanyo
1	U1	BMA250	IC, Digital, Triaxial Acceleration Sensor	LGA	BMA250	Bosch
1	U2	CC430F5147IRGZ	IC, Microcontroller SoC with RF Core	VQFN	CC430F5147IRGZ	TI
1	U3	0868AT43A0020E	868MHz Chip Antenna		3216 0868AT43A0020E	Johnson Technology
1	U4	TPS62740DSS	IC, Ultra Low IQ Step Down Converter	WSON	TPS62740DSS	TI
1	Y1	32KHz	Crystal, Tuning Fork, 30kHz - 200kHz, SMD	6.7 x 1.40 mm	MS3V-T1R	Micro Crystal AG
1	Y2	BALUN868MHz	IC, 868MHz Impedance Matched/Balun/BP	0.079 x 0.049 inch	0868BM15C0001S	Johnson Technology
1	Y3	26MHz	Crystal, Short-Range Wireless	0.98 x 0.126 inch	NX3225SA-xxxM-STD-CSR-3	Nihon Dempa Kogyo

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